

DESCRIPTIVE ABSTRACT

5           Assembly of sensors formed as an imager with a detection brick including a photosensitive material, a brick for addressing and optionally processing signals from the sensor(s), an interconnection brick located between the detection brick and the addressing brick, this brick including connection pads, characterized in that the photosensitive material of the detection brick contains polymorphous silicon.

10           The invention also relates to a method for the making of the latter.

Fig. 8